

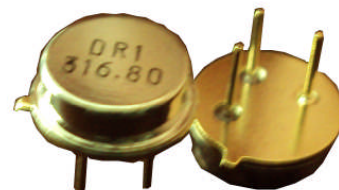
SAW Resonators/Filter

TO-39 (One Port)

Features

◆RoHS Compliant

◆Through hole type



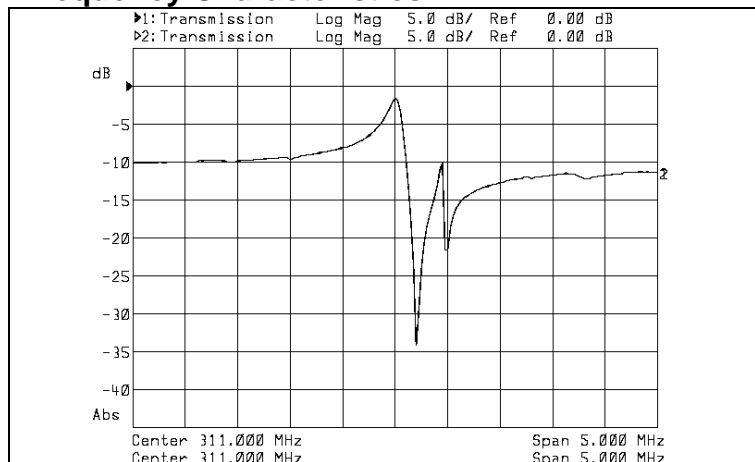
Maximum Rating

Item	Value
DC Voltage V_{DC}	10V
AC Voltage V_{PP}	10V (50Hz/60Hz)
Operation Temperature	-40℃ to +85℃
Storage Temperature	-45℃ to +90℃
RF Power Dissipation	0dBm

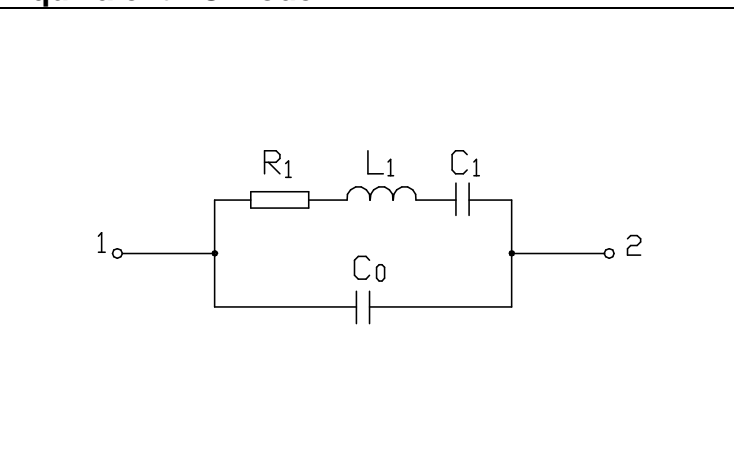
Electronic Characteristics

Item	Specifications
Nominal Frequency Range	300.000MHz to 868.350MHz
Tolerance	±75KHz

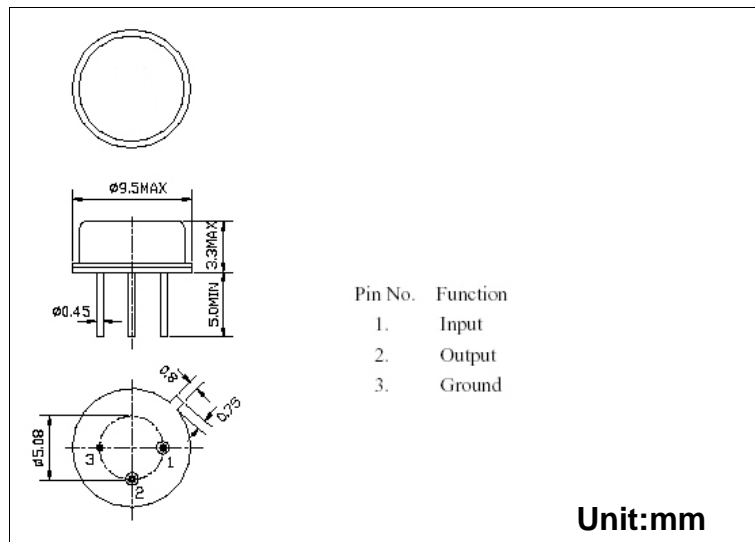
Frequency Characteristics



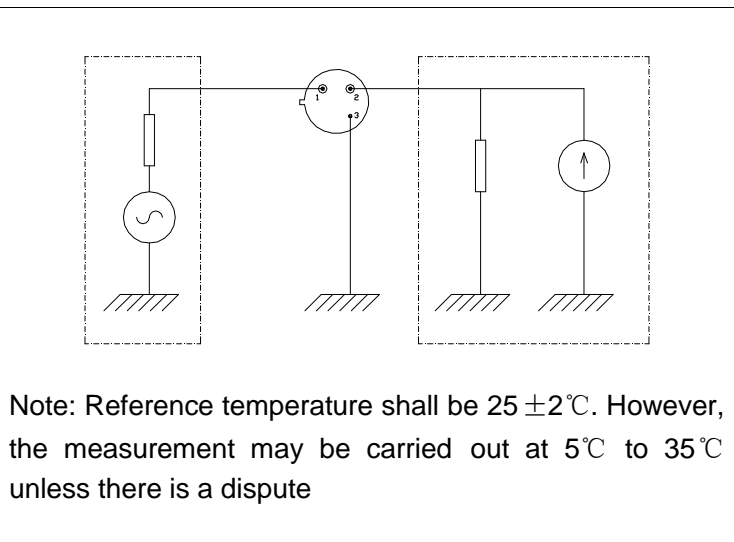
Equivalent LC Model



Dimensions



Test Circuit



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Reliability

Mechanical Shock	The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s^2 , duration 6 milliseconds.
Vibration Fatigue	The components shall remain within the electrical specifications after loaded vibration at 20 Hz, amplitude 1.5mm, for 2 hours.
Terminal Strength	The components shall remain within the electrical specifications after pulled 2 kgs weight for 10 seconds towards an axis of each terminal.
High Temperature Storage	The components shall remain within the electrical specifications after being kept at the $85^\circ\text{C} \pm 2^\circ\text{C}$ for 48 hours, then kept at room temperature for 2 hours.
Low Temperature Storage	The components shall remain within the electrical specifications after being kept at the $-40^\circ\text{C} \pm 2^\circ\text{C}$ for 48 hours, then kept at room temperature for 2 hours.
Temperature Cycle	The components shall remain within the electrical specifications after 5 cycles of high and low temperature testing (one cycle: 80°C for 30 minutes $\rightarrow 25^\circ\text{C}$ for 5 minutes $\rightarrow -25^\circ\text{C}$ for 30 minutes) then kept at room temperature for 2 hours.
Solder-heat Resistance	The components shall remain within the electrical specifications after dipped in the solder at 260°C for 10 ± 1 seconds, then kept at room temperature for 2 hours. (Terminal must be dipped leaving 1.5 mm from the case).
Solderability	Solderability of terminal shall be kept at more than 80% after dipped in the solder flux at $230^\circ\text{C} \pm 5^\circ\text{C}$ for 5 ± 1 seconds.

Remarks

Static voltage	Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.
Ultrasonic cleaning	Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.
Soldering	Only leads of component may be soldered. Please avoid soldering another part of component.

